production boardstack

carrier (x4)

SCROD

HV

front

70.93

110.87
SCROD status

- new generation FPGA (Zynq '045)
- RAM onboard
- CAL distribution
- 14 fully-populated prototypes built; being distributed to:
  - SLAC, PNNL, IU, SC, Pitt, KEK
carrier design status

- new generation FPGA (Zynq '030)
- two-stage amplifier
- better thermal coupling:
  - thicker copper layers, blind vias, via-in-PAD
  - component placement based largely on thermal requirements
carrier design status

new 2-stage amp

carrier revE (in fab now)
worst-case PCB temperature: 43.4°C
worst-case junction temperature: 81.5°C
production schedule